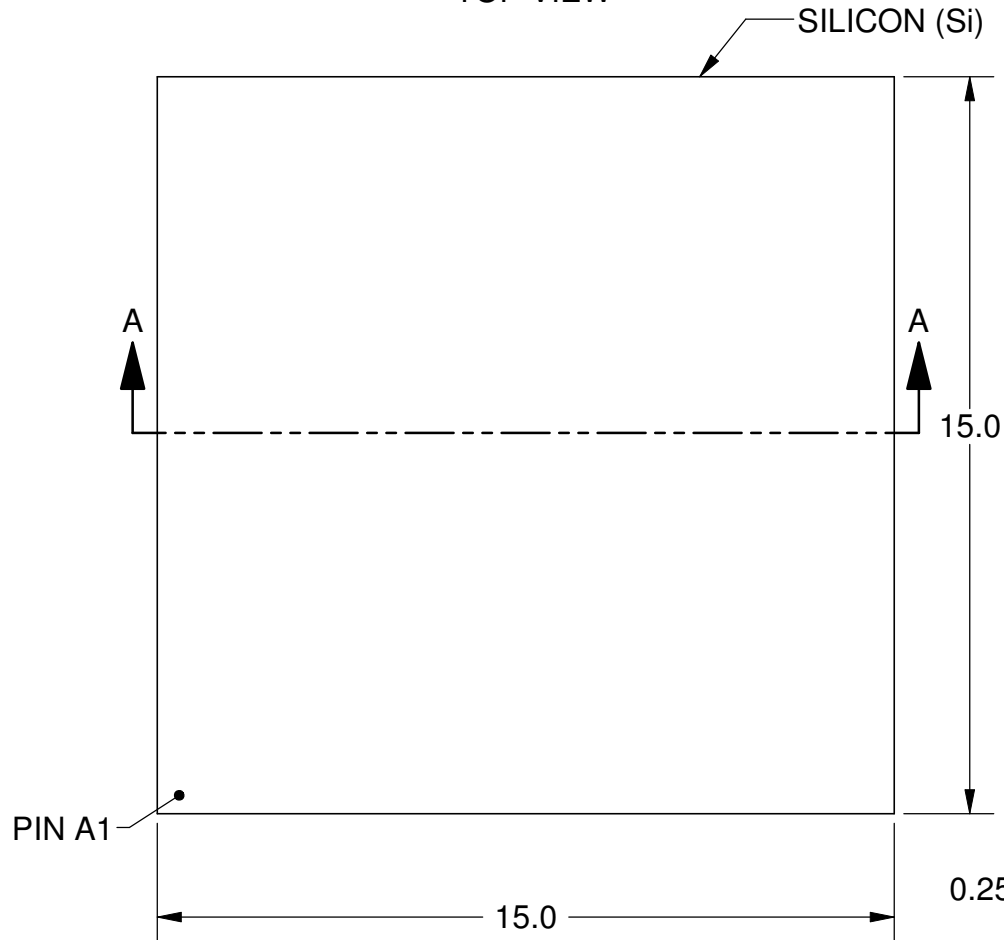
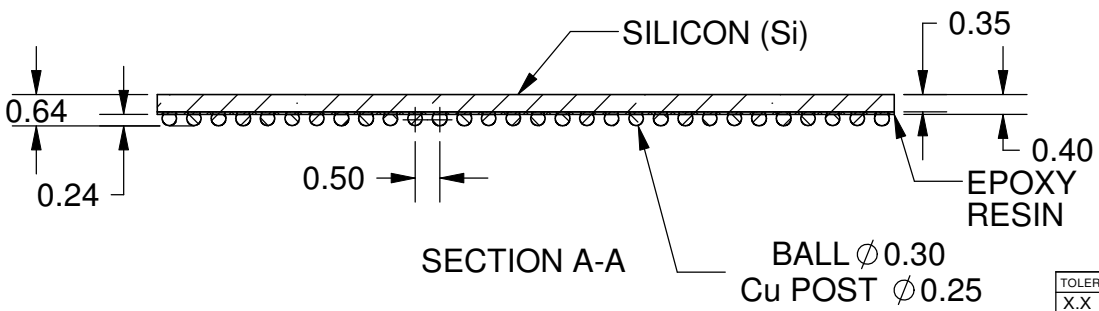
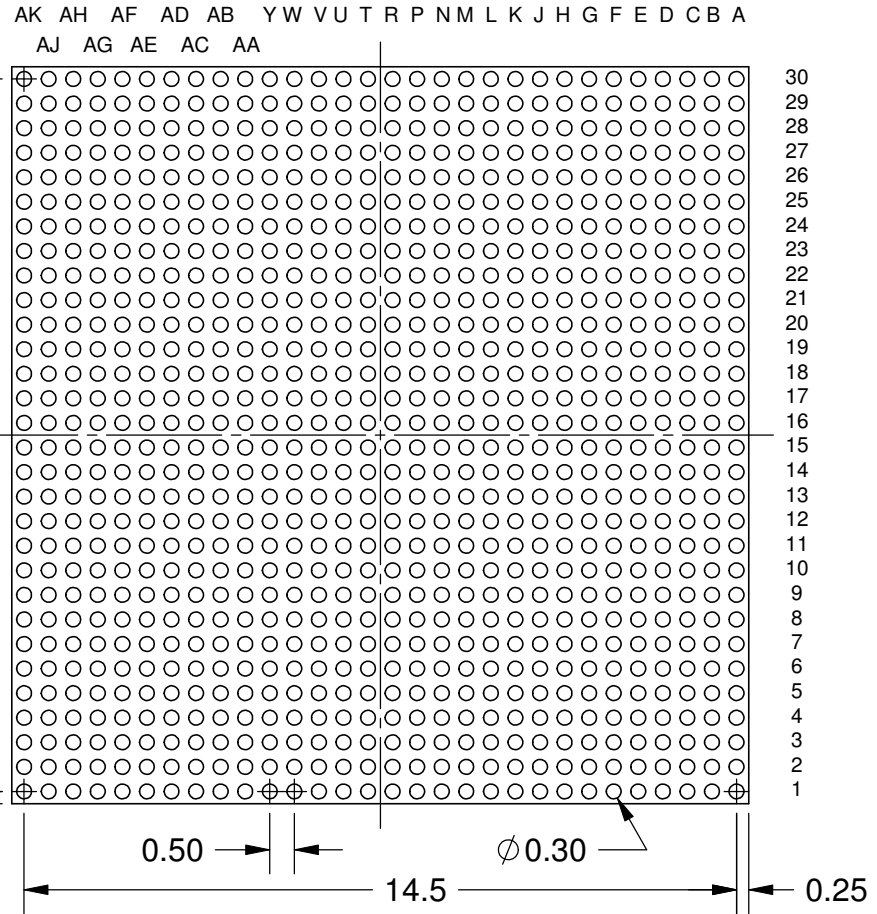


TOP VIEW



BALL VIEW



- Notes: (Unless Otherwise Specified).  
 1) ALL DIMENSIONS ARE IN MM.  
 2) SOLDER BALL ALLOY:  
 STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).  
 SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).  
 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.  
 4) NON-SOLDER MASK DEFINED PAD.  
 5) PAD Cu DIAMETER: 0.25mm.  
 6) SUBSTRATE MATERIAL: Si (SILICON).  
 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP900T.5C-DC307D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP900T.5C1-DC307D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.3	DRAWN J. Hines	12/28/2010
X.XX	+/- 0.03		
X.XXX	+/- 0.003		
ANGLES +/- 0.5°		ENG	
ALL DIMENSIONS IN		MFG	
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA	
THIRD ANGLE PROJECTION		CUST	
		REVISED	

**TopLine**®

TITLE **WLP900T.5C-DC307D**  
**900-BALL P=0.5mm (TEG0510)**

SCALE 6.5:1	SIZE A	DRAWING NO. 553072	REV A
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DO NOT SCALE DRAWING

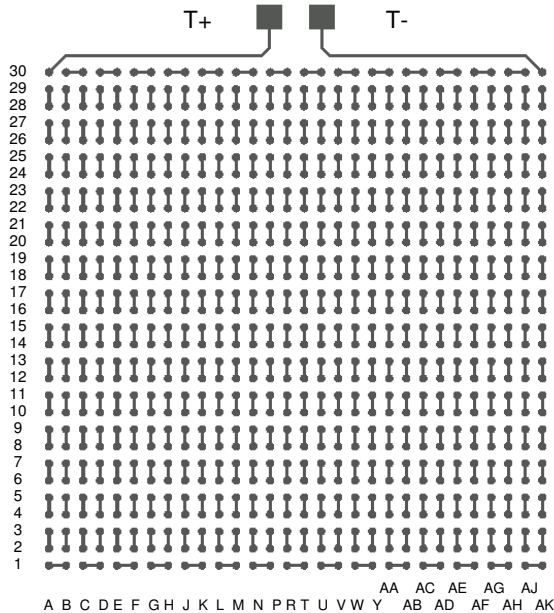
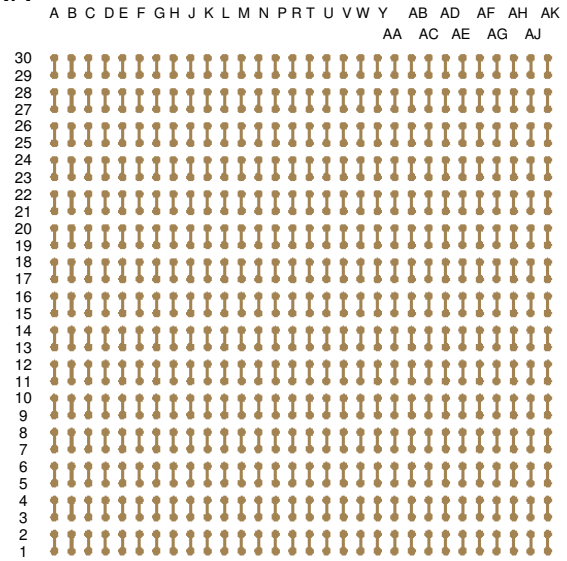
SHEET 1 OF 2

# DAISY CHAIN PATTERN



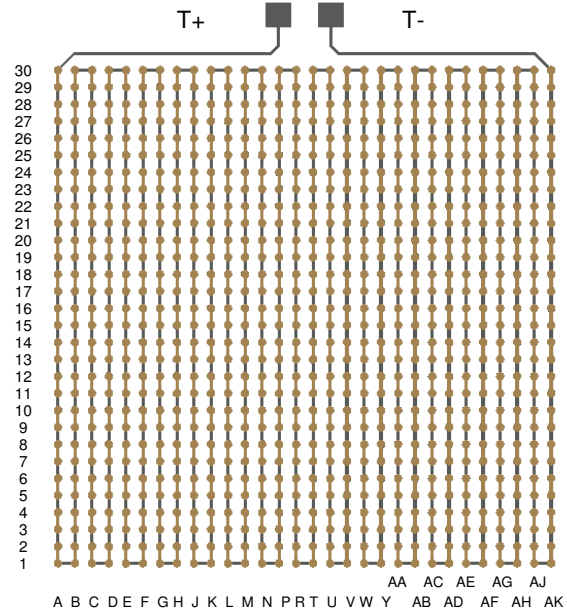
BALL VIEW

BOTTOM SIDE  
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)



## TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.25mm (9.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

<b>TopLine</b> ®			
TITLE    WLP900T.5C-DC307D			
900-BALL P=0.5mm (TEG0510)			
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	553072	A
DO NOT SCALE DRAWING			SHEET 2 OF 2